1.8V / 2.5V, 10GHz ÷4 Clock Divider with CML Outputs

Multi-Level Inputs w/ Internal Termination

Description

The NB7V33M is a differential $\div 4$ Clock divider with asynchronous reset. The differential Clock inputs incorporate internal 50 Ω termination resistors and will accept LVPECL, CML and LVDS logic levels. The NB7V33M produces a $\div 4$ output copy of an input Clock operating up to 10 GHz with minimal jitter. The Reset pin is asserted on the rising edge. Upon powerup, the internal flip – flops will attain a random state; the Reset allows for the synchronization of multiple NB7V33M's in a system. The 16 mA differential CML output provides matching internal 50 Ω termination which guarantees 400 mV output swing when externally receiver terminated with 50 Ω to V_{CC} .

The NB7V33M is the $\div 4$ version of the NB7V32M ($\div 2$) and is offered in a low profile 3 mm x 3 mm 16-pin QFN package.

The NB7V33M is a member of the GigaComm[™] family of high performance clock products. Application notes, models, and support documentation are available at www.onsemi.com.

Features

- Maximum Input Clock Frequency > 10 GHz, typical
- 260 ps Typical Propagation Delay
- 35 ps Typical Rise and Fall Times
- Differential CML Outputs, 400 mV Peak-to-Peak, Typical
- Operating Range: $V_{CC} = 1.71 \text{ V}$ to 2.625 V with GND = 0 V
- Internal 50 Ω Input Termination Resistors
- Random Clock Jitter < 0.8 ps RMS
- QFN-16 Package, 3 mm x 3 mm
- -40°C to +85°C Ambient Operating Temperature
- These are Pb-Free Devices



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MARKING DIAGRAM* 16 1 NB7V 33M ALYW ■ CASE 485G

A = Assembly Location

L = Wafer Lot

Y = Year W = Work Week

■ = Pb-Free Package (Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

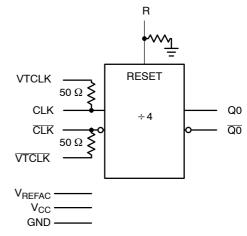


Figure 1. Simplified Logic Diagram

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

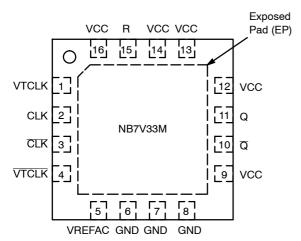


Figure 2. Pin Configuration (Top View)

Table 1. TRUTH TABLE

CLK	CLK	R	Q	Q
х	х	Н	L	Н
Z	W	L	CLK ÷ 4	CLK ÷ 4

Z = Low to High Transition W = High to Low Transition X = Don't Care

Table 2. PIN DESCRIPTION

Pin	Name	I/O	Description
1	VTCLK	-	Internal 50 Ω Termination Pin for CLK
2	CLK	LVPECL, CML, LVDS Input	Non-inverted Differential CLK Input. Note 1.
3	CLK	LVPECL, CML, LVDS Input	Inverted Differential CLK Input. Note 1.
4	VTCLK	-	Internal 50 Ω Termination Pin for $\overline{\text{CLK}}$
5	VREFAC	-	Internally Generated Output Voltage Reference for Capacitor-Coupled Inputs, Only
6	GND	-	Negative Supply Voltage
7	GND	-	Negative Supply Voltage
8	GND	-	Negative Supply Voltage
9	Vcc	-	Positive Supply Voltage. Note 2.
10	Q	CML Output	Inverted Differential Output
11	Q	CML Output	Non-Inverted Differential Output
12	Vcc	-	Positive Supply Voltage. Note 2.
13	Vcc	-	Positive Supply Voltage. Note 2.
14	Vcc	-	Positive Supply Voltage. Note 2.
15	R	LVCMOS Input	Asynchronous Reset Input. Internal 75 k Ω pulldown to GND.
16	Vcc	-	Positive Supply Voltage. Note 2.
-	EP	-	The Exposed Pad (EP) on the QFN-16 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat-sinking conduit. The pad is electrically connected to the die, and must be electrically and thermally connected to GND on the PC board.

In the differential configuration when the input termination pins (VTCLK/VTCLK) are connected to a common termination voltage or left open, and if no signal is applied on CLK/CLK input, then the device will be susceptible to self-oscillation. Q/Q outputs have internal 50 Ω source termination resistors.

^{2.} All V_{CC} and GND pins must be externally connected to a power supply for proper operation.

Table 3. ATTRIBUTES

Characteristic	Value				
ESD Protection Human Body Model Machine Model		> 4 kV > 200 V			
R _{PD} – Reset Input Pulldown Resistor	75 kΩ				
Moisture Sensitivity (Note 3) QFN16		Level 1			
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in			
Transistor Count	190				
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test					

^{3.} For additional information, see Application Note AND8003/D.

Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	Positive Power Supply	GND = 0 V		3.0	V
V _{IN}	Positive Input Voltage	GND = 0 V		-0.5 to V _{CC} +0.5	V
V _{INPP}	Differential Input Voltage D − D			1.89	V
I _{IN}	Input Current Through R _T (50 Ω Resistor)			± 40	mA
I _{OUT}	Output Current Through R _T (50 Ω Resistor)			±40	mA
I _{VFREFAC}	VREFAC Sink/Source Current			±1.5	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient) (Note 4)	0 lfpm 500 lfpm	QFN-16 QFN-16	42 35	°C/W
θJC	Thermal Resistance (Junction-to-Case) (Note 4)		QFN-16	4	°C/W
T _{sol}	Wave Solder Pb-Free			265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

^{4.} JEDEC standard multilayer board – 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

Table 5. DC CHARACTERISTICS POSITIVE CML OUTPUT $V_{CG} = 1.71 \text{ V}$ to 2.625 V; GND = 0 V; $T_{\Delta} = -40 ^{\circ}\text{C}$ to $85 ^{\circ}\text{C}$ (Note 5)

Symbol	Characteristic	Min	Тур	Max	Unit
POWER:	SUPPLY CURRENT	•			
I _{CC}	Power Supply Current (Inputs and Outputs Open) $VCC = 2.5 V \pm 5.9 VCC = 1.8 V \pm 5.9$		95 85	115 100	mA
CML OU	TPUTS	•			
V _{OH}	Output HIGH Voltage (Note 6) VCC = 2.5 VCC = 1.8		V _{CC} – 10 2490 1790	V _{CC} 2500 1800	mV
V _{OL}	Output LOW Voltage (Note 6) VCC = 2.5 VCC = 1.8	V _{CC} – 600	V _{CC} – 550 1950 V _{CC} – 500 1300	V _{CC} – 450 2050 V _{CC} – 400 1400	mV
DIFFERE	NTIAL INPUTS DRIVEN SINGLE-ENDED (Note 7) (Figures 5 & 6)				
V_{th}	Input Threshold Reference Voltage Range (Note 8)	1050		V _{CC} – 100	mV
V_{IH}	Single-ended Input HIGH Voltage	V _{th} + 100		V_{CC}	mV
V_{IL}	Single-ended Input LOW Voltage	GND		V _{th} – 100	mV
V_{ISE}	Single-ended Input Voltage (V _{IH} - V _{IL})	200		1200	mV
VREFAC					
V _{REFAC}	Output Reference Voltage @100 μ A for Capacitor– Coupled Inputs, Only V_{CC} = 2.5 V_{CC} = 1.8 V_{CC}			V _{CC} - 500 V _{CC} - 450	mV
DIFFERE	NTIAL INPUTS DRIVEN DIFFERENTIALLY (Figures 7 & 8) (Note 9)				
V_{IHD}	Differential Input HIGH Voltage	1100		V_{CC}	mV
V_{ILD}	Differential Input LOW Voltage	GND		V _{CC} – 100	mV
V_{ID}	Differential Input Voltage (V _{IHD} - V _{ILD})	100		1200	mV
V _{CMR}	Input Common Mode Range (Differential Configuration, Note 10) (Figure 9)	1050		V _{CC} - 50	mV
I _{IH}	Input HIGH Current (VTx/VTx Open)	-150		150	μΑ
I _{IL}	Input LOW Current (VTx/VTx Open)	-150		150	μΑ
CONTRO	DL INPUT (Reset pin)				
V _{IH}	Input HIGH Voltage for Control Pin	V _{CC} - 200		V_{CC}	mV
V_{IL}	Input LOW Voltage for Control Pin	GND		200	mV
I _{IH}	Input HIGH Current	-150		150	μΑ
I _{IL}	Input LOW Current	-150		150	μΑ
TERMINA	ATION RESISTORS	-			
R _{TIN}	Internal Input Termination Resistor	45	50	55	Ω
R _{TOUT}	Internal Output Termination Resistor	45	50	55	Ω

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 5. Input and output parameters vary 1:1 with V_{CC} .
- 6. CML outputs loaded with $50-\Omega$ to V_{CC} for proper operation.
- 7. Vth, V_{IH}, V_{IL}, and V_{ISE} parameters must be complied with simultaneously.
 8. Vth is applied to the complementary input when operating in single-ended mode.
- 9. V_{IHD} , V_{ILD} , V_{ID} and V_{CMR} parameters must be complied with simultaneously.
- 10. V_{CMR} min varies 1:1 with GND, V_{CMR} max varies 1:1 with V_{CC} . The V_{CMR} range is referenced to the most positive side of the differential input signal.

Table 6. AC CHARACTERISTICS $V_{CC} = 1.71 \text{ V}$ to 2.625 V; GND = 0 V; $T_A = -40 ^{\circ}\text{C}$ to $85 ^{\circ}\text{C}$ (Note 11)

Symbol	Characteristic		Min	Тур	Max	Unit
f _{MAX}	Maximum Input Clock Frequency		10	11		GHz
V _{OUTPP}	Output Voltage Amplitude (@ $V_{INPPmin}$) $f_{in} \le 10 \text{ GHz}$ (Note 12) (Figure 3)	Output Voltage Amplitude (@ $V_{INPPmin}$) $f_{in} \le 10 \text{ GHz}$ (Note 12) (Figure 3)		400		mV
t _{PLH} , t _{PHL}	Propagation Delay to Differential Outputs, @ 1 GHz, measured at differential crosspoint	CLK/CLK to Q, Q R to Q, Q	150 500	200 600	350 700	ps
t _{PLH} TC	Propagation Delay Temperature Coefficient			50		∆fs/°C
t _{skew}	Duty Cycle Skew (Note 13) Device – Device skew (tpdmax – tpdmin)				20 50	ps
t _{RR}	Reset Recovery (See Figure 16)		550	135		ps
t _{PW}	Minimum Pulse Width R		500	200		ps
t _{DC}	Output Clock Duty Cycle (Reference Duty Cycle = 50%) f _{in} ≤ 10 GHz		45	50	55	%
ФΝ	Phase Noise, f _c = 1 GHz 10 kHz 100 kHz 1 MHz 10 MHz 20 MHz 40 MHz			-144 -147 -152 -152 -152 -153		dBc
$t_{\int \Phi N}$	Integrated Phase Jitter (Figure x) f _C = 1 GHz, 12 kHz - 20 MHz Offset			35		fs
t _{JITTER}	RJ – Output Random Jitter (Note 14) $f_{in} \leq 10.0 \text{ GHz}$			0.2	0.8	ps RMS
V _{INPP}	Input Voltage Swing (Differential Configuration) (Figure 11) (Note 15)		200		1200	mV
t _r , t _f	Output Rise/Fall Times @ 1 GHz (20% – 80%), Q, \overline{Q}			35	60	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 11. Measured using a 1 GHz, V_{INPP}min, 50% duty-cycle clock source. All output loading with external 50 Ω to V_{CC}. Input edge rates 40 ps (20% 80%).
- 12. Output voltage swing is a single-ended measurement operating in differential mode.
- 13. Duty cycle skew is defined only for differential operation when the delays are measured from cross-point of the inputs to the cross-point of the outputs. Duty cycle skew is measured between differential outputs using the deviations of the sum of Tpw- and Tpw+ @ 1 GHz. Skew is measured between outputs under identical transitions and conditions.
- 14. Additive RMS jitter with 50% duty cycle clock signal.
- 15. Input voltage swing is a single-ended measurement operating in differential mode.

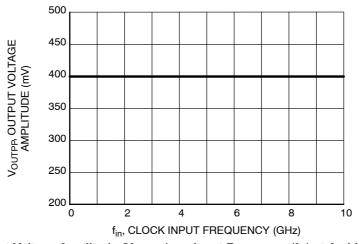


Figure 3. Output Voltage Amplitude (V_{OUTPP}) vs. Input Frequency (f_{in}) at Ambient Temperature (Typical)

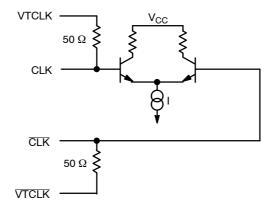


Figure 4. Input Structure

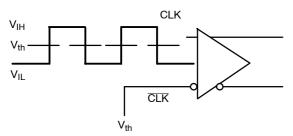


Figure 5. Differential Input Driven Single-Ended

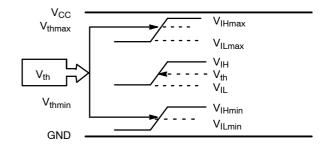


Figure 6. V_{th} Diagram

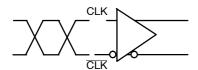


Figure 7. Differential Inputs Driven Differentially

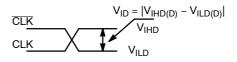


Figure 8. Differential Inputs Driven Differentially

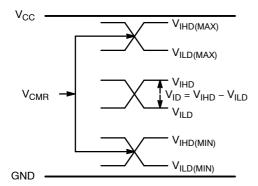


Figure 9. V_{CMR} Diagram

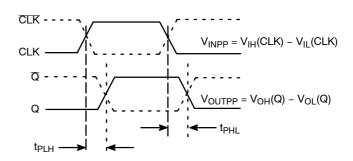


Figure 10. AC Reference Measurement

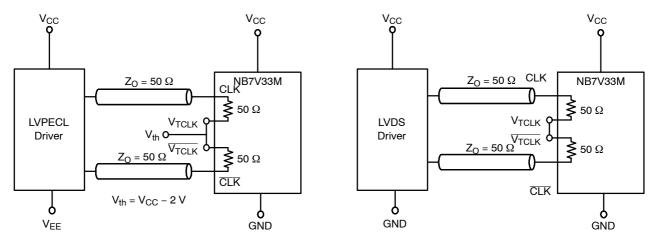


Figure 11. LVPECL Interface

Figure 12. LVDS Interface

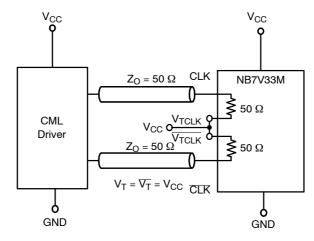


Figure 13. Standard 50 Ω Load CML Interface

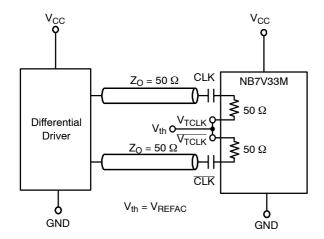


Figure 14. Capacitor–Coupled Differential Interface $(V_{TCLK}/\overline{V_{TCLK}}$ Connected to V_{REFAC} ; V_{REFAC} Bypassed to Ground with 0.1 μF Capacitor)

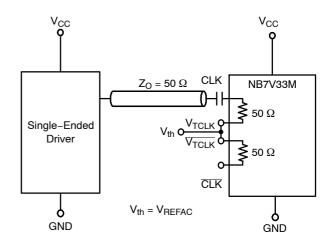


Figure 15. Capacitor–Coupled Single–Ended Interface (V_{TCLK}/V_{TCLK} Connected to V_{REFAC} ; V_{REFAC} Bypassed to Ground with 0.1 μF Capacitor)

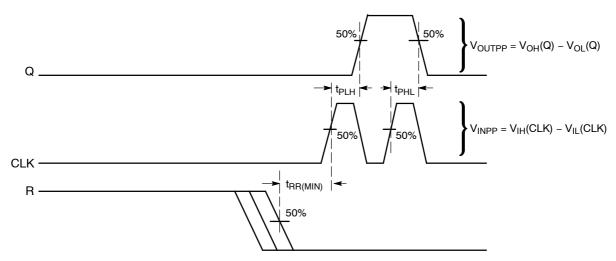


Figure 16. AC Reference Measurement (Timing Diagram)

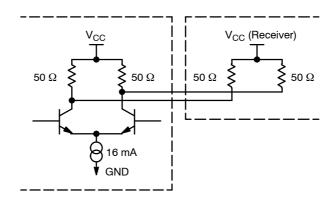


Figure 17. Typical CML Output Structure and Termination

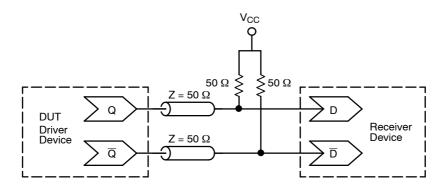


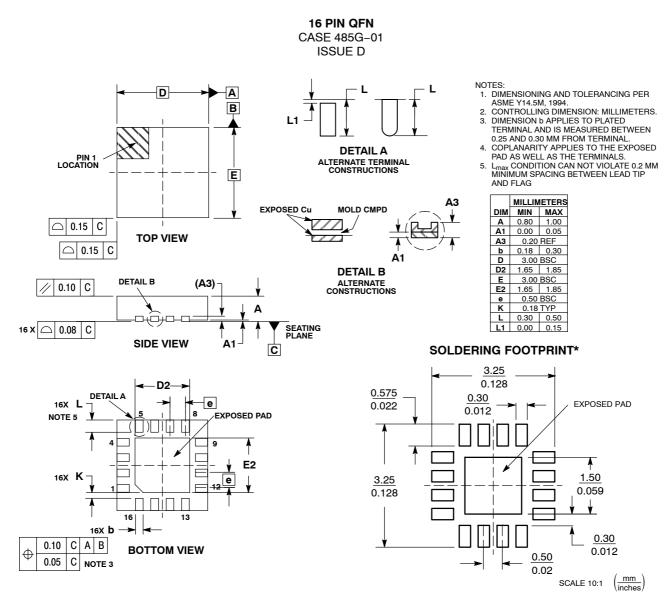
Figure 18. Typical Termination for CML Output Driver and Device Evaluation

DEVICE ORDERING INFORMATION1

Device	Package	Shipping [†]
NB7V33MMNG	QFN-16 (Pb-Free)	123 Units / Rail
NB7V33MMNHTBG	QFN-16 (Pb-Free)	100 / Tape & Reel
NB7V33MMNTXG	QFN-16 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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